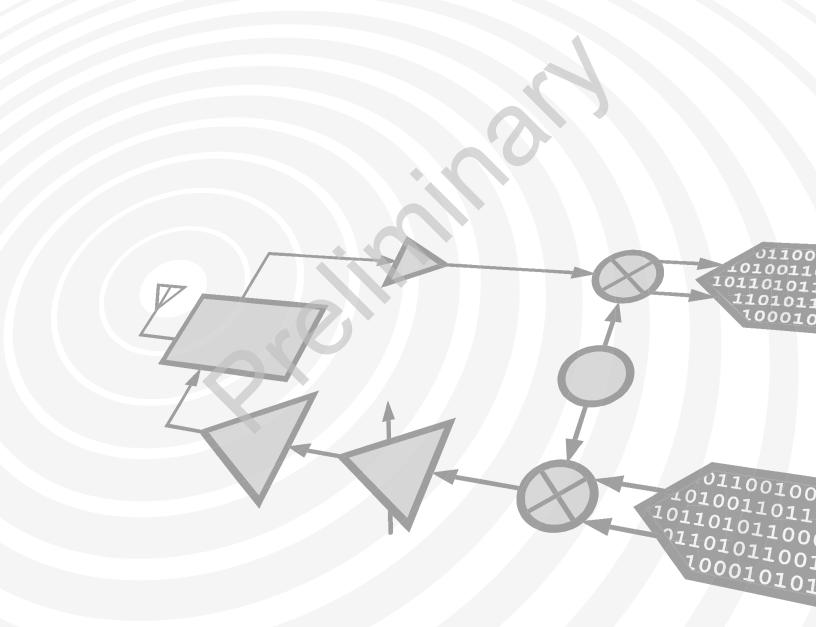




# Analog Devices Welcomes Hittite Microwave Corporation



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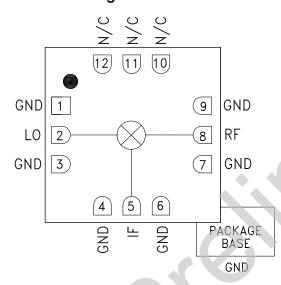
# GaAs MMIC FUNDAMENTAL MIXER, 14 - 26 GHz

### **Typical Applications**

The HMC260ALC3B is ideal for:

- Point-to-Point Radios
- Point-to-Multi-Point Radios & VSAT
- Test Equipment & Sensors
- Military End-Use

### **Functional Diagram**



### **Features**

Passive: No DC Bias Required

Input IP3: +20 dBm LO/RF Isolation: 40 dB

Wide IF Bandwidth: DC - 8 GHz

12 Lead Ceramic 3x3 mm SMT Package: 9mm<sup>2</sup>

### General Description

HMC260ALC3B general double balanced mixer in a leadless compliant SMT package that can be used as an upconverter or downconverter between 14 This 26 GHz. mixer requires no external components The matching circuitry. HMC260ALC3B provides excellent LO to RF and LO to IF suppression due to optimized balun structures. The mixer operates with LO drive levels above +9 dBm. The HMC260ALC3B eliminates the need for wire bonding, allowing use of surface mount manufacturing techniques.

## Electrical Specifications, $T_A = +25^{\circ}$ C, IF= 1 GHz, LO= +13 dBm\*

Parameter	Min.	Тур.	Max.	Min.	Тур.	Max.	Units
Frequency Range, RF & LO		14 - 18			18 - 26		GHz
Frequency Range, IF	DC - 8		DC - 8			GHz	
Conversion Loss		7.5	10.5		9	12	dB
Noise Figure (SSB)		7.5	10.5		9	12	dB
LO to RF Isolation	34	40		30	35		dB
LO to IF Isolation	24	30		24	35		dB
RF to IF Isolation	15	25		25	30		dB
IP3 (Input)		18			20		dBm
IP2 (Input)		50			50		dBm
1 dB Gain Compression (Input)		12			14		dBm

 $<sup>^*</sup>$ Unless otherwise noted, all measurements performed as downconverter, IF= 1 GHz.



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### **MxN Spurious Outputs**

	nLO						
mRF	0	1	2	3	4		
0	xx	-2	17	xx	xx		
1	18	0	38	50	78		
2	82	74	71	65	84		
3	xx	90	95	77	90		
4	xx	xx	93	98	104		

RF = 18 GHz @ -10 dBm LO = 17 GHz @ +13 dBm

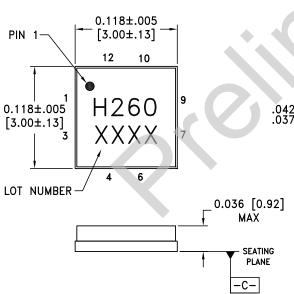
All values in dBc below the IF output power level.

### **Absolute Maximum Ratings**

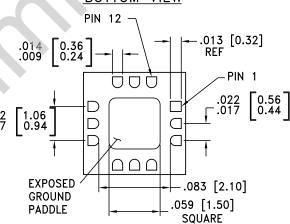
RF / IF Input	+15 dBm	
LO Drive	+27 dBm	
Channel Temperature	150 °C	
Continuous Pdiss (Ta = 85 °C) (derate 3.95 mW/°C above 85 °C)	260 mW	
Thermal Resistance (junction to ground paddle)	253 °C/W	
Storage Temperature	-65 to +150 °C	
Operating Temperature	-40 to +85 °C	
ESD Sensitivity (HBM)	Class 1A	



# Outline Drawing



### **BOTTOM VIEW**



### NOTES:

- 1. PACKAGE BODY MATERIAL: ALUMINA.
- 2. LEAD AND GROUND PADDLE PLATING: GOLD FLASH OVER NICKEL.
- 3. DIMENSIONS ARE IN INCHES (MILLIMETERS).
- 4. LEAD SPACING TOLERANCE IS NON-CUMULATIVE.
- 5. CHARACTERS TO BE HELVETICA MEDIUM, .025 HIGH, BLACK INK, OR LASER MARK LOCATED APPROX. AS SHOWN.
- 6. PACKAGE WARP SHALL NOT EXCEED 0.05MM DATUM C -
- 7. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.